

SYSTEM AND METHOD FOR REDUCING TEMPERATURE VARIATION
DURING BURN IN

ABSTRACT

Systems and methods for reducing temperature variation during burn-in
5 testing. In one embodiment, power consumed by an integrated circuit under test
is measured. An ambient temperature associated with the integrated circuit is
measured. A desired junction temperature of the integrated circuit is achieved by
adjusting a body bias voltage of the integrated circuit. By controlling
temperature of individual integrated circuits, temperature variation during burn-
10 in testing can be reduced.